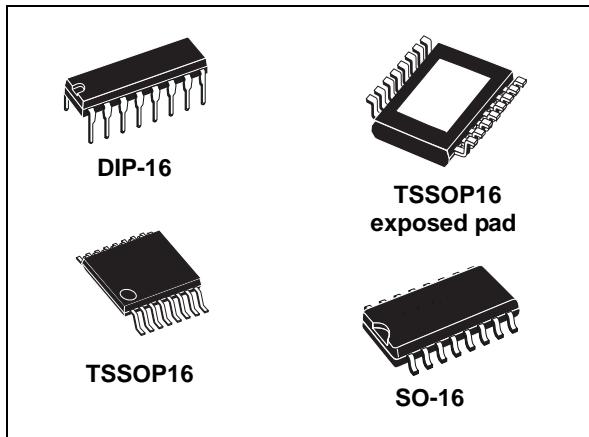


## Low voltage, low current power 8-bit shift register

Datasheet - production data



### Features

- Low voltage power supply down to 3 V
- 8 constant current output channels
- Adjustable output current through external resistor
- Serial data IN/parallel data OUT
- 3.3 V micro driver-able
- Output current: 5-100 mA
- 30 MHz clock frequency
- Available in high thermal efficiency TSSOP exposed pad
- ESD protection 2.5 kV HBM, 200 V MM

### Description

The STP08CP05 is a monolithic, low voltage, low current, power 8-bit shift register designed for LED panel displays. The STP08CP05 contains an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. In the output stage, eight regulated current sources were designed to provide 5-100 mA constant current to drive the LEDs, the output current setup time is 11 ns (typ), thus improving the system performance.

The STP08CP05 is backward compatible in functionality and footprint with STP8C/L596. Through an external resistor, users can adjust the STP08CP05 output current, controlling in this way the light intensity of LEDs, in addition, user can adjust LED's brightness intensity from 0% to 100% via OE pin.

The STP08CP05 guarantees a 20 V output driving capability, allowing users to connect more LEDs in series. The high clock frequency, 30 MHz, also satisfies the system requirement of high volume data transmission. The 3.3 V of voltage supply is useful for applications that interface with any micro from 3.3 V. Compared with a standard TSSOP package, the TSSOP exposed pad increases heat dissipation capability by a 2.5 factor.

**Table 1. Device summary**

Order codes	Package	Packaging
STP08CP05B1R	DIP-16	25 parts per tube
STP08CP05MTR	SO-16 (Tape and reel)	2500 parts per reel
STP08CP05TTR	TSSOP16 (Tape and reel)	2500 parts per reel
STP08CP05XTTR	TSSOP16 exposed pad (Tape and reel)	2500 parts per reel

## Contents

<b>1</b>	<b>Summary description</b>	<b>3</b>
1.1	Pin connection and description	3
<b>2</b>	<b>Block diagram</b>	<b>4</b>
<b>3</b>	<b>Maximum rating</b>	<b>5</b>
3.1	Absolute maximum ratings	5
3.2	Thermal data	5
3.3	Recommended operating conditions	6
<b>4</b>	<b>Electrical characteristics</b>	<b>7</b>
<b>5</b>	<b>Switching characteristics</b>	<b>8</b>
<b>6</b>	<b>Equivalent circuit and outputs</b>	<b>9</b>
<b>7</b>	<b>Truth table and timing diagram</b>	<b>11</b>
7.1	Truth table	11
7.2	Timing diagram	11
<b>8</b>	<b>Typical characteristics</b>	<b>14</b>
<b>9</b>	<b>Test circuit</b>	<b>17</b>
<b>10</b>	<b>Package mechanical data</b>	<b>18</b>
<b>11</b>	<b>Packaging mechanical data</b>	<b>27</b>
<b>12</b>	<b>Revision history</b>	<b>29</b>

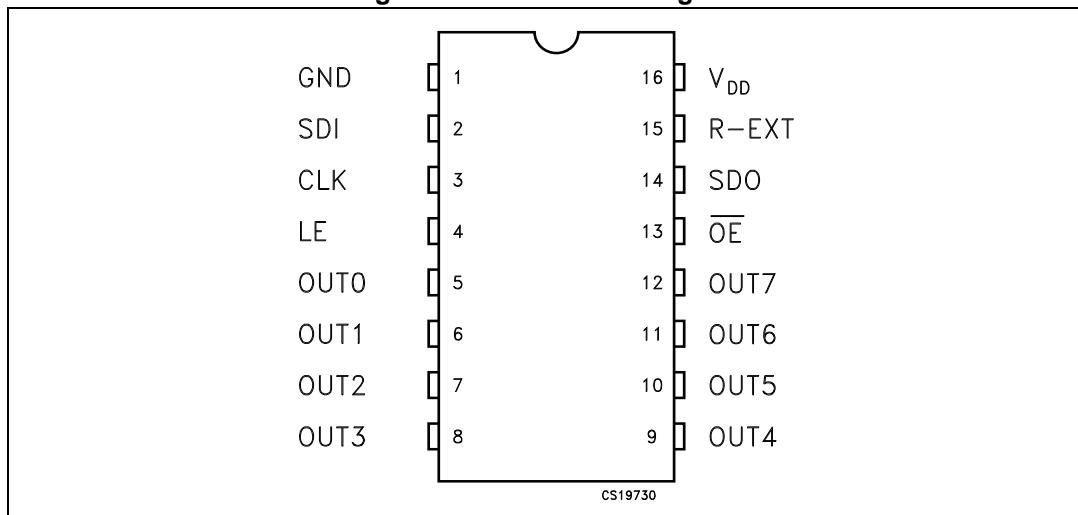
# 1 Summary description

**Table 2. Typical current accuracy**

Output voltage	Current accuracy		Output current
	Between bits	Between ICs	
$\geq 1.3 \text{ V}$	$\pm 1.5\%$	$\pm 3\%$	20 to 100 mA

## 1.1 Pin connection and description

**Figure 1. Connections diagram**



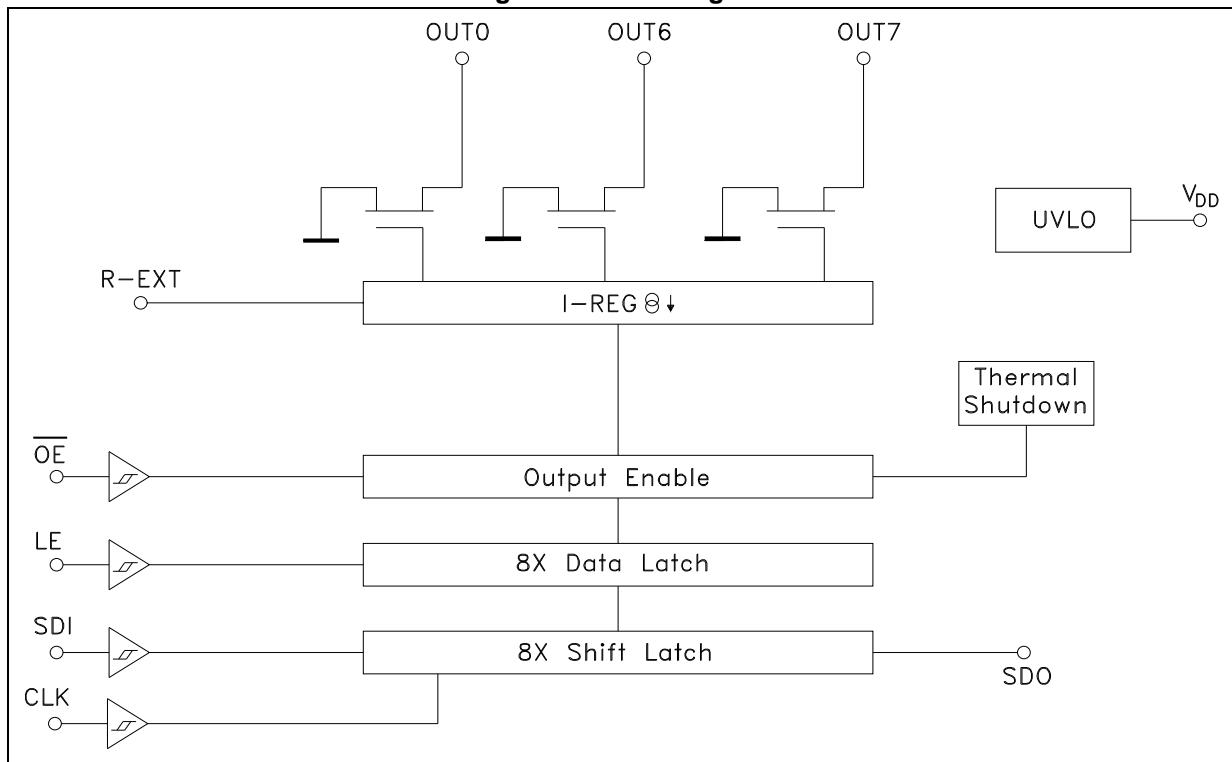
*Note:* The exposed pad should be electrically connected to a metal land electrically isolated or connected to ground.

**Table 3. Pin description**

Pin N°	Symbol	Name and function
1	GND	Ground terminal
2	SDI	Serial data input terminal
3	CLK	Clock input terminal
4	LE	Latch input terminal
5-12	OUT 0-7	Output terminal
13	$\overline{\text{OE}}$	Output enable input terminal (active low)
14	SDO	Serial data out terminal
15	R-EXT	Constant current programming
16	$V_{DD}$	5 V supply voltage terminal

## 2 Block diagram

Figure 2. Block diagram



### 3 Maximum rating

Stressing the device above the rating listed in the “absolute maximum ratings” table may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### 3.1 Absolute maximum ratings

**Table 4. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DD}$	Supply voltage $I_{GND}$	0 to 7	V
$V_O$	Output voltage	-0.5 to 20	V
$I_O$	Output current	100	mA
$I_{GND}$	GND terminal current	800	mA
$f_{CLK}$	Clock frequency	50	MHz
$T_{OPR}$	Operating temperature range	-40 to +125	°C
$T_{STG}$	Storage temperature range	-55 to +150	°C

#### 3.2 Thermal data

**Table 5. Thermal data**

Symbol	Parameter	DIP-16	SO-16	TSSOP16	TSSOP16 <sup>(1)</sup> exposed pad	Unit
$R_{thJA}$	Thermal resistance junction-ambient	90	125	140	37.5	°C/W

1. The exposed-pad should be soldered to the PBC to realize the thermal benefits

### 3.3 Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
$V_{DD}$	Supply voltage		3.0		5.5	V
$V_O$	Output voltage				20	V
$I_O$	Output current	OUTn	5		100	mA
$I_{OH}$	Output current	SERIAL-OUT			+1	mA
$I_{OL}$	Output current	SERIAL-OUT			-1	mA
$V_{IH}$	Input voltage		0.7 $V_{DD}$		$V_{DD}+0.3$	V
$V_{IL}$	Input voltage		-0.3		0.3 $V_{DD}$	V
$t_{wLAT}$	LE pulse width	$V_{DD} = 3.0 \text{ to } 5.0 \text{ V}$	20			ns
$t_{wCLK}$	CLK pulse width		20			ns
$t_{wEN}$	$\overline{OE}$ pulse width		200			ns
$t_{SETUP(D)}$	Setup time for DATA		7			ns
$t_{HOLD(D)}$	Hold time for DATA		4			ns
$t_{SETUP(L)}$	Setup time for LATCH		15			ns
$f_{CLK}$	Clock frequency	Cascade operation <sup>(1)</sup>			30	MHz

1. In order to achieve high cascade data transfer, please consider  $t_p/t_f$  timings carefully.

## 4 Electrical characteristics

$V_{DD} = 3.3 \text{ V to } 5 \text{ V}$ ,  $T = 25^\circ\text{C}$ , unless otherwise specified.

Table 7. Electrical characteristics

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
$V_{IH}$	Input voltage high level		$0.7 V_{DD}$		$V_{DD}$	V
$V_{IL}$	Input voltage low level		GND		$0.3V_{DD}$	V
$I_{OH}$	Output leakage current	$V_{OH} = 20 \text{ V}$		0.5	10	$\mu\text{A}$
$V_{OL}$	Output voltage (Serial-OUT)	$I_{OL} = 1 \text{ mA}$		0.03	0.4	V
$V_{OH}$	Output voltage (Serial-OUT)	$I_{OH} = -1 \text{ mA}$	$V_{OH} - V_{DD} = -0.4 \text{ V}$			V
$I_{OL1}$	Output current	$V_O = 0.3 \text{ V}, R_{ext} = 3.9 \text{ k}\Omega$	4.25	5	5.75	mA
$I_{OL2}$		$V_O = 0.3 \text{ V}, R_{ext} = 970 \Omega$	19.4	20	20.6	
$I_{OL3}$		$V_O = 1.3 \text{ V}, R_{ext} = 190 \Omega$	97	100	103	
$\Delta I_{OL1}$	Output current error between bit (All Output ON)	$V_O = 0.3 \text{ V} R_{EXT} = 3.9 \text{ k}\Omega$		$\pm 5$	$\pm 8$	%
$\Delta I_{OL2}$		$V_O = 0.3 \text{ V} R_{EXT} = 970 \Omega$		$\pm 1.5$	$\pm 2.75$	
$\Delta I_{OL3}$		$V_O = 1.3 \text{ V} R_{EXT} = 190 \Omega$		$\pm 1.2$	$\pm 2.5$	
$R_{SIN(up)}$	Pull-up resistor		150	300	600	K $\Omega$
$R_{SIN(down)}$	Pull-down resistor		100	200	400	K $\Omega$
$I_{DD(OFF1)}$	Supply current (OFF)	$R_{EXT} = 980 \Omega$ OUT 0 to 7 = OFF		4	5	mA
$I_{DD(OFF2)}$		$R_{EXT} = 250 \Omega$ OUT 0 to 7 = OFF		11.2	13.5	
$I_{DD(ON1)}$	Supply current (ON)	$R_{EXT} = 980 \Omega$ OUT 0 to 7 = ON		4.5	5	
$I_{DD(ON2)}$		$R_{EXT} = 250 \Omega$ OUT 0 to 7 = ON		11.7	13.5	
Thermal	Thermal protection <sup>(1)</sup>			170		°C

1. Guaranteed by design (not tested)  
The thermal protection switches OFF only the outputs

## 5 Switching characteristics

$V_{DD} = 5 \text{ V}$ ,  $T = 25^\circ\text{C}$ , unless otherwise specified.

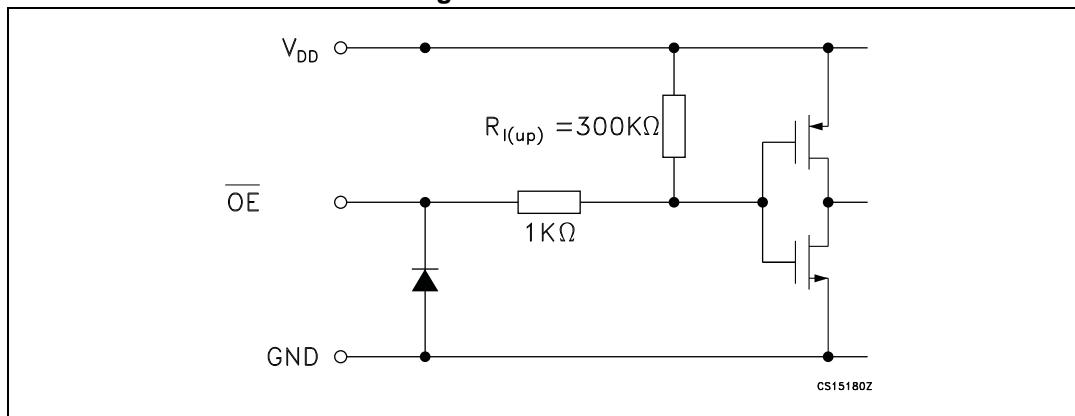
**Table 8. Switching characteristics**

Symbol	Parameter	Test conditions		Min	Typ	Max	Unit	
$t_{PLH1}$	Propagation delay time, <u>CLK</u> -OUTn, LE = H, OE = L	$V_{DD} = 3.3 \text{ V}$ $V_{IL} = \text{GND}$ $I_O = 20 \text{ mA}$ $R_{EXT} = 1 \text{ K}\Omega$	$V_{DD} = 3.3 \text{ V}$		35	50	ns	
	Propagation delay time, <u>LE</u> -OUTn, OE = L		$V_{DD} = 5 \text{ V}$		18	28		
			$V_{DD} = 3.3 \text{ V}$		48	74	ns	
	Propagation delay time, OE -OUTn, LE = H		$V_{DD} = 5 \text{ V}$		30	50		
			$V_{DD} = 3.3 \text{ V}$		55	82	ns	
			$V_{DD} = 5 \text{ V}$		37	58		
	Propagation delay time, CLK-SDO		$V_{DD} = 3.3 \text{ V}$		21	28	ns	
			$V_{DD} = 5 \text{ V}$		17	22		
	Propagation delay time, <u>CLK</u> -OUTn, LE = H, OE = L		$V_{DD} = 3.3 \text{ V}$		11	17	ns	
			$V_{DD} = 5 \text{ V}$		7	11		
	Propagation delay time, <u>LE</u> -OUTn, OE = L		$V_{DD} = 3.3 \text{ V}$		24	40	ns	
			$V_{DD} = 5 \text{ V}$		21	31		
	Propagation delay time, OE -OUTn, LE = H		$V_{DD} = 3.3 \text{ V}$		20	35	ns	
			$V_{DD} = 5 \text{ V}$		18	28		
	Propagation delay time, CLK-SDO		$V_{DD} = 3.3 \text{ V}$		24	32	ns	
			$V_{DD} = 5 \text{ V}$		19	25		
	Output fall time 10~90% of voltage waveform		$V_{DD} = 3.3 \text{ V}$		26	40	ns	
			$V_{DD} = 5 \text{ V}$		11	17		
	Output rise time 90~10% of voltage waveform		$V_{DD} = 3.3 \text{ V}$		5	10	ns	
			$V_{DD} = 5 \text{ V}$		4	8		
$t_r$	CLK rise time <sup>(1)</sup>					5000	ns	
$t_f$	CLK fall time <sup>(1)</sup>					5000	ns	

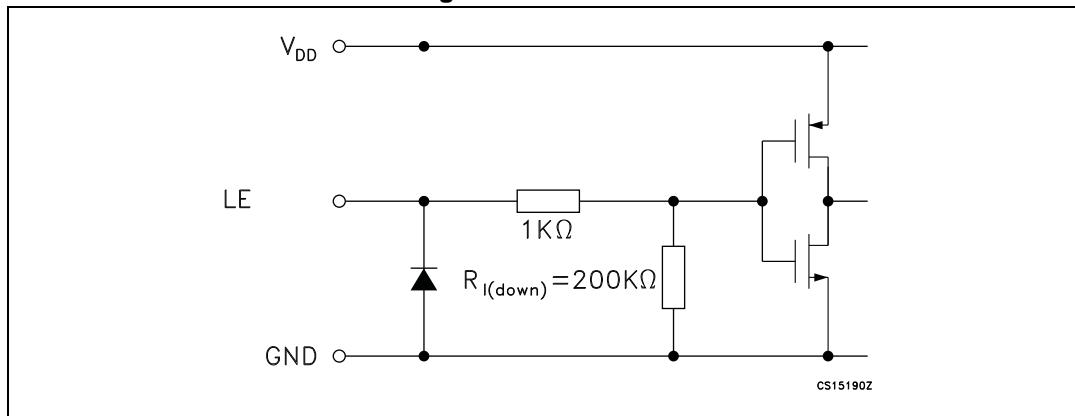
1. In order to achieve high cascade data transfer, please consider tr/tf timings carefully.

## 6 Equivalent circuit and outputs

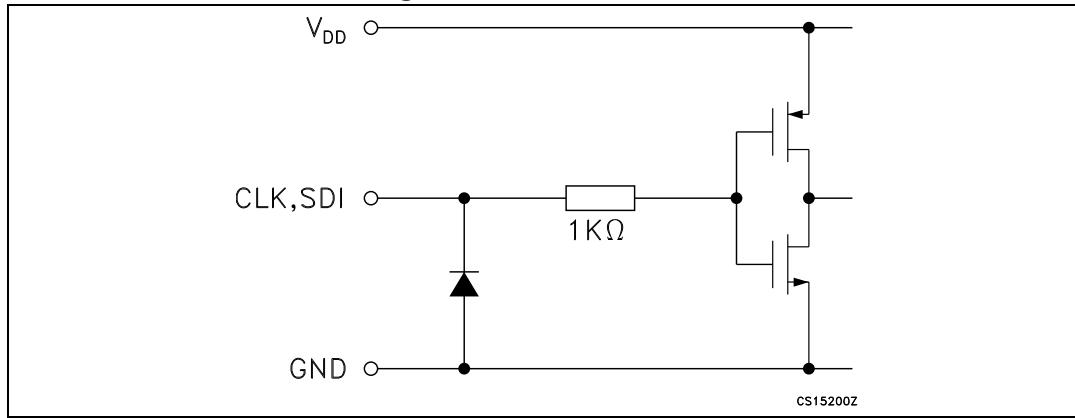
**Figure 3.  $\overline{OE}$  terminal**

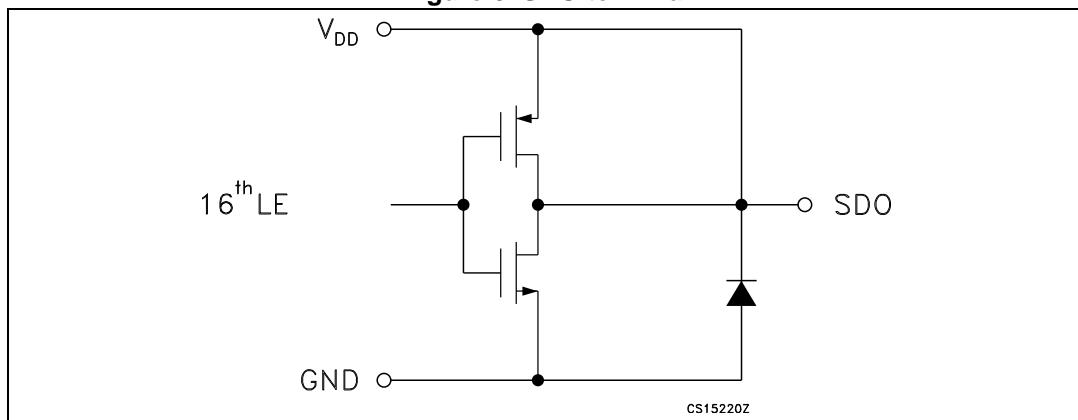


**Figure 4. LE terminal**



**Figure 5. CLK, SDI terminal**



**Figure 6. SDO terminal**

## 7 Truth table and timing diagram

### 7.1 Truth table

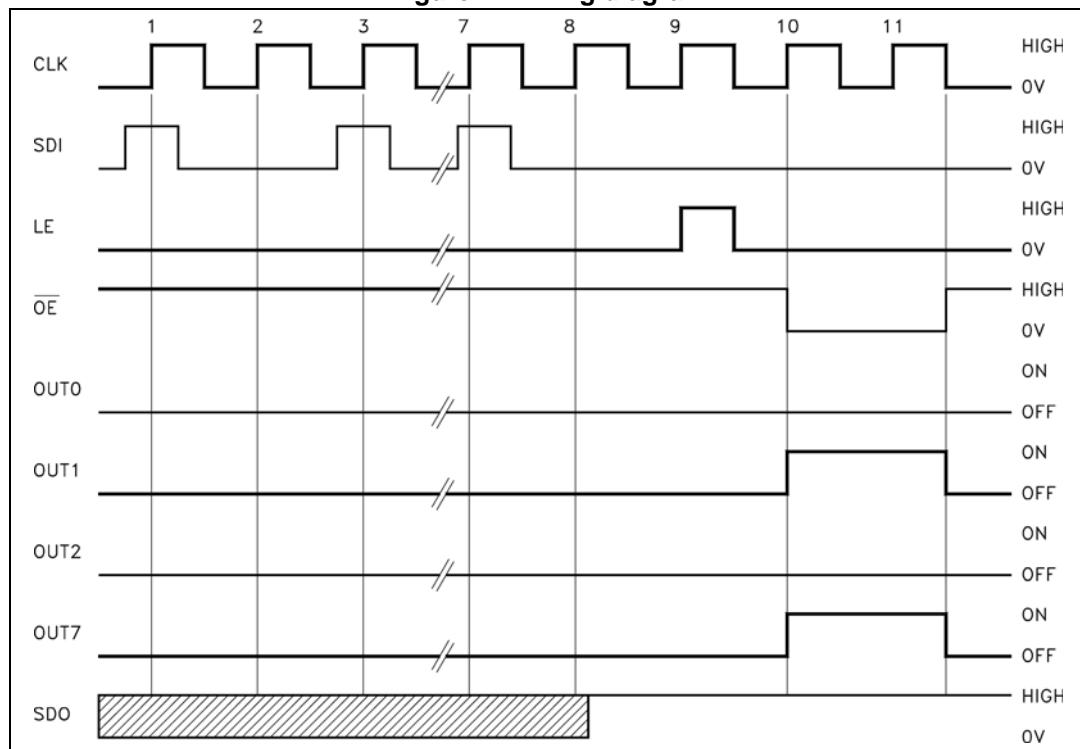
**Table 9. Truth table**

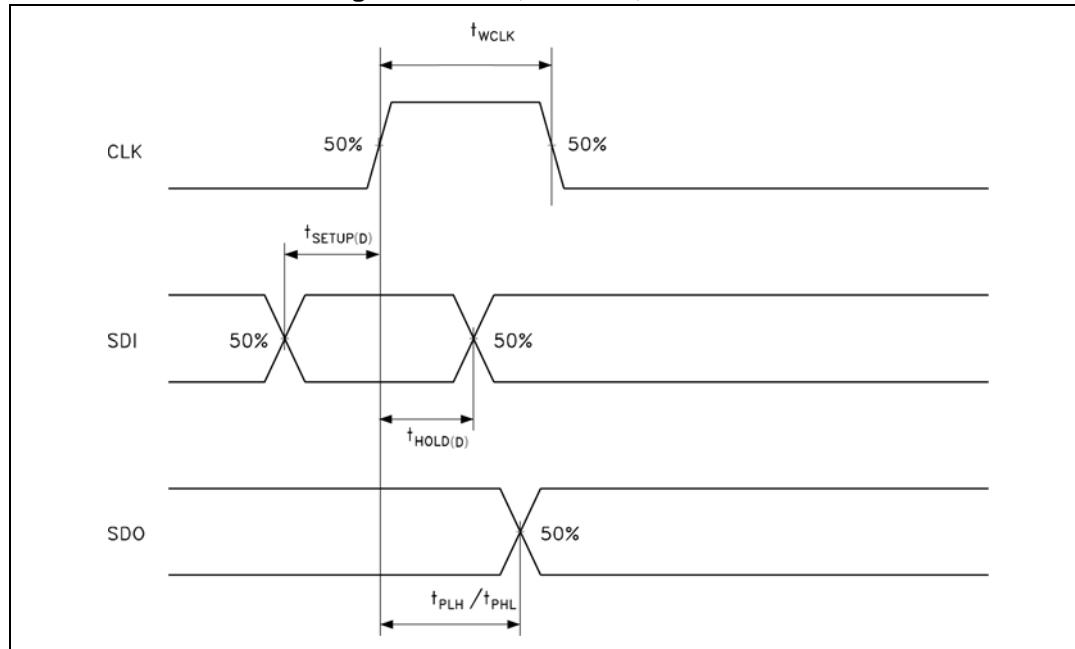
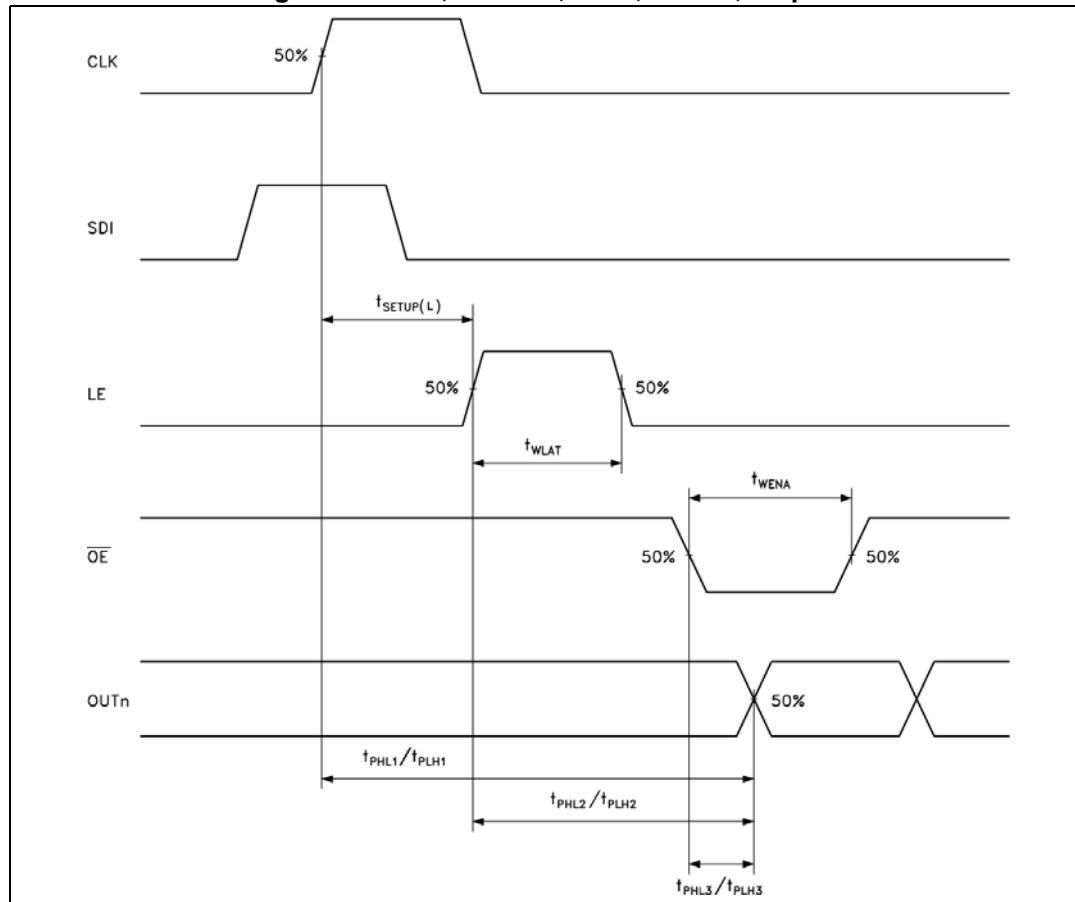
Clock	$\overline{LE}$	$\overline{OE}$	SDI	$\overline{OUT0} \dots \overline{OUT0} \dots \overline{OUT7}$	SDO
	H	L	Dn	Dn ..... Dn -5 ..... Dn -7	Dn -7
	L	L	Dn + 1	No change	Dn -7
	H	L	Dn + 2	$\overline{Dn +2} \dots \overline{Dn -3} \dots \overline{Dn -5}$	Dn -5
	X	L	Dn + 3	$\overline{Dn +2} \dots \overline{Dn -3} \dots \overline{Dn -5}$	Dn -5
	X	H	Dn + 3	OFF	Dn -5

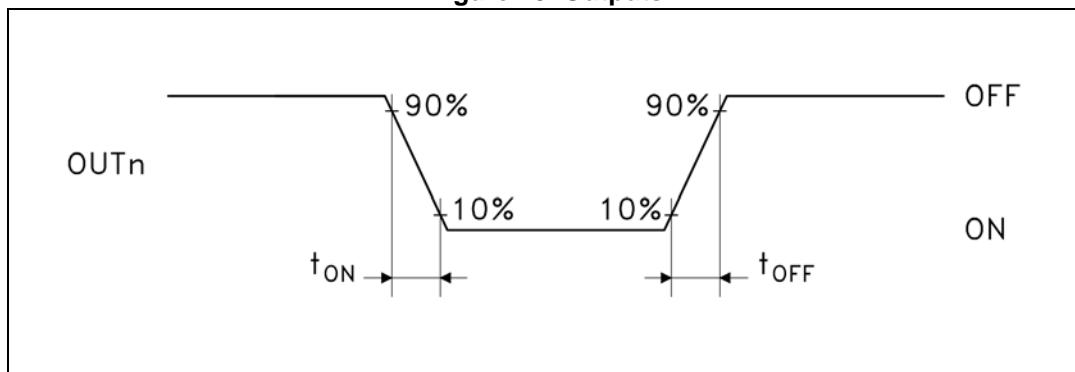
Note:  $OUT0$  to  $OUT7$  = ON when  $Dn = H$ ;  $OUT0$  to  $OUT7$  = OFF when  $Dn = L$ .

### 7.2 Timing diagram

**Figure 7. Timing diagram**

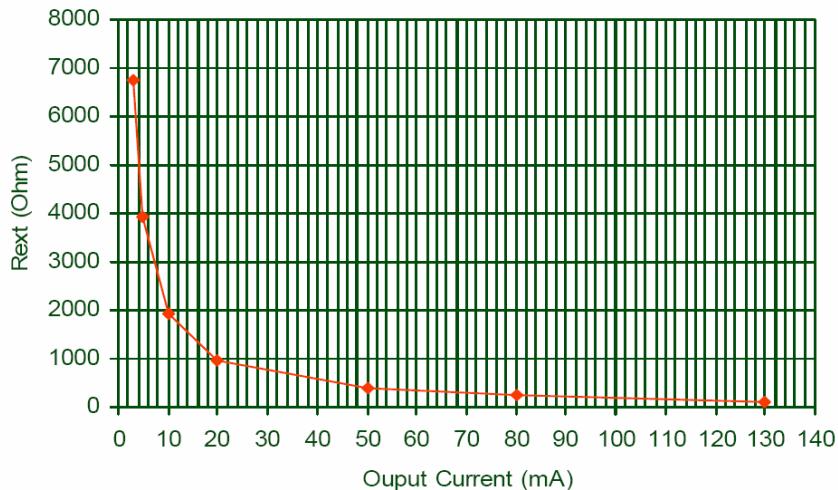


**Figure 8. Clock, serial-in, serial-out****Figure 9. Clock, serial-in, latch, enable, outputs**

**Figure 10. Outputs**

## 8 Typical characteristics

Figure 11. Output current-R<sub>EXT</sub> resistor

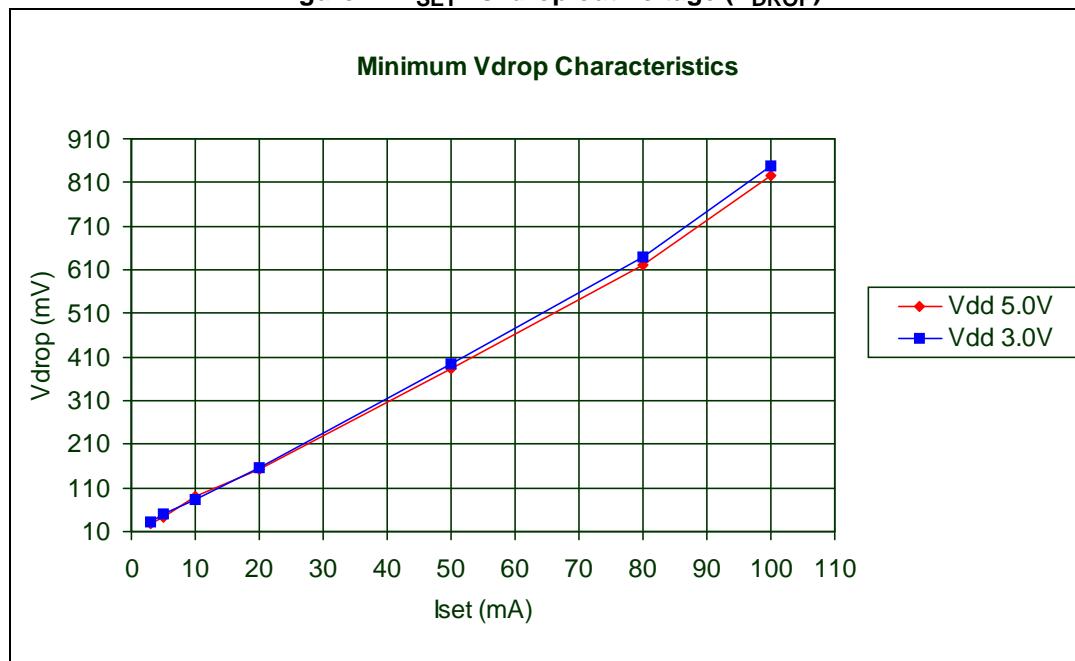


T<sub>A</sub> = 25 °C, Iset = 3 mA; 5 mA; 10 mA; 20 mA; 50 mA; 80 mA; Max

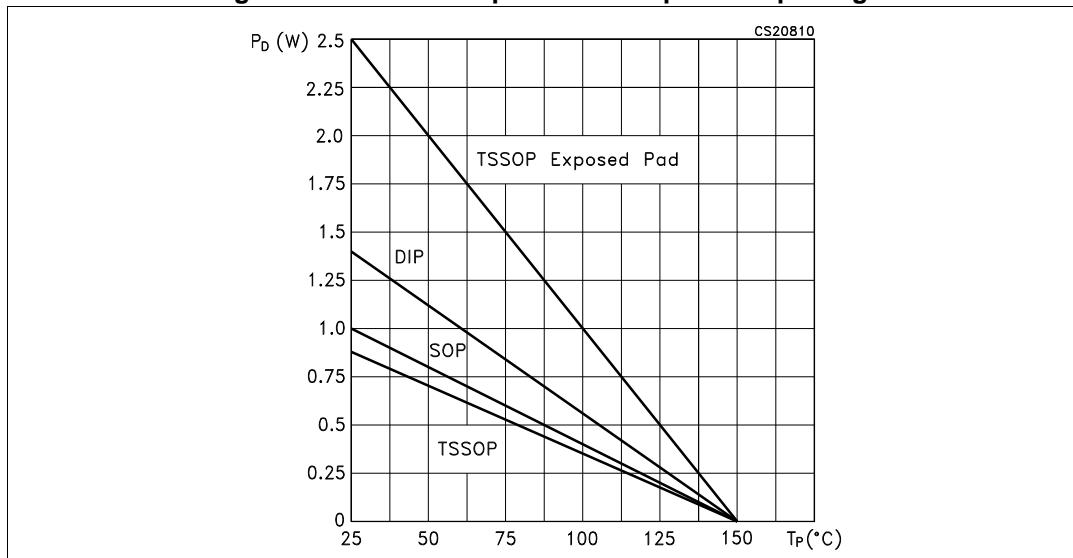
Table 10. Output current-R<sub>EXT</sub> resistor

Output current (mA)	3	5	10	20	50	80	130
R <sub>ext</sub> (Ω)	6740	3930	1913	963	386	241	124

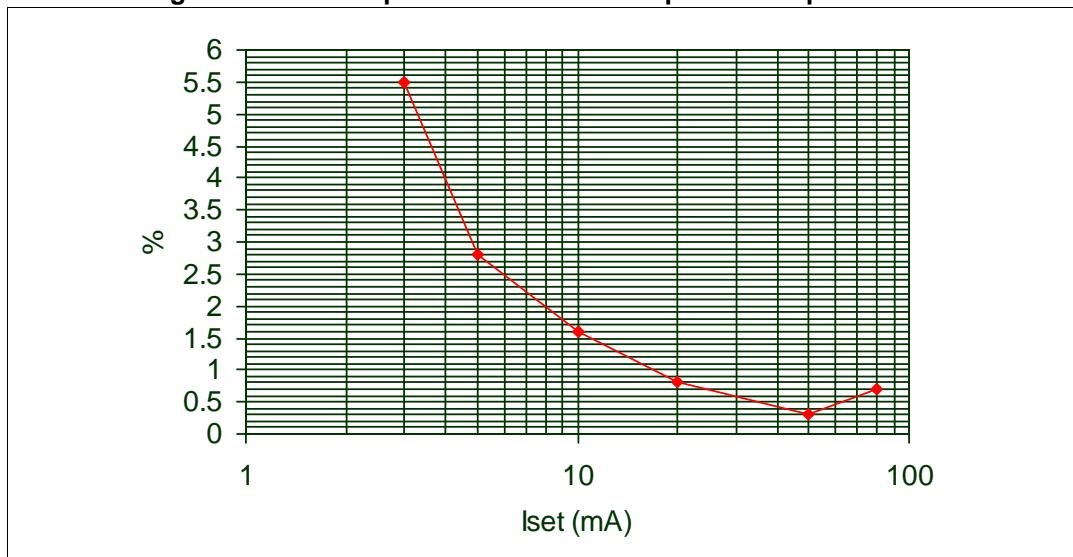
Note: Maximum output current capabilities setting was 130 mA applying an R<sub>ext</sub> = 124 Ω.

Figure 12.  $I_{SET}$  vs. drop out voltage ( $V_{DROP}$ )Table 11.  $I_{SET}$  vs drop out voltage ( $V_{DROP}$ )

$V_{DD}$ (V)	$I_{SET}$ (mA)	$R_{EXT}$ ( $\Omega$ )	$V_{DROP\ min}$ (mV)	$V_{DROP\ max}$ (mV)	$V_{DROP\ AVG}$ (mV)
3	3	6470	30.6	31.2	30.93
	5	3930	46.5	52.9	48.63
	10	1910	80.9	100	82.26
	20	963	150	161	157
	50	386	392	396	394.3
	80	241	636	646	640.3
	100	192	846	850	848
5	3	6470	25.6	29	26.96
	5	3930	40.8	41.7	41.16
	10	1910	80.1	105	89.2
	20	963	153	154	154
	50	386	379	386	382
	80	241	618	626	621
	100	192	825	830	827

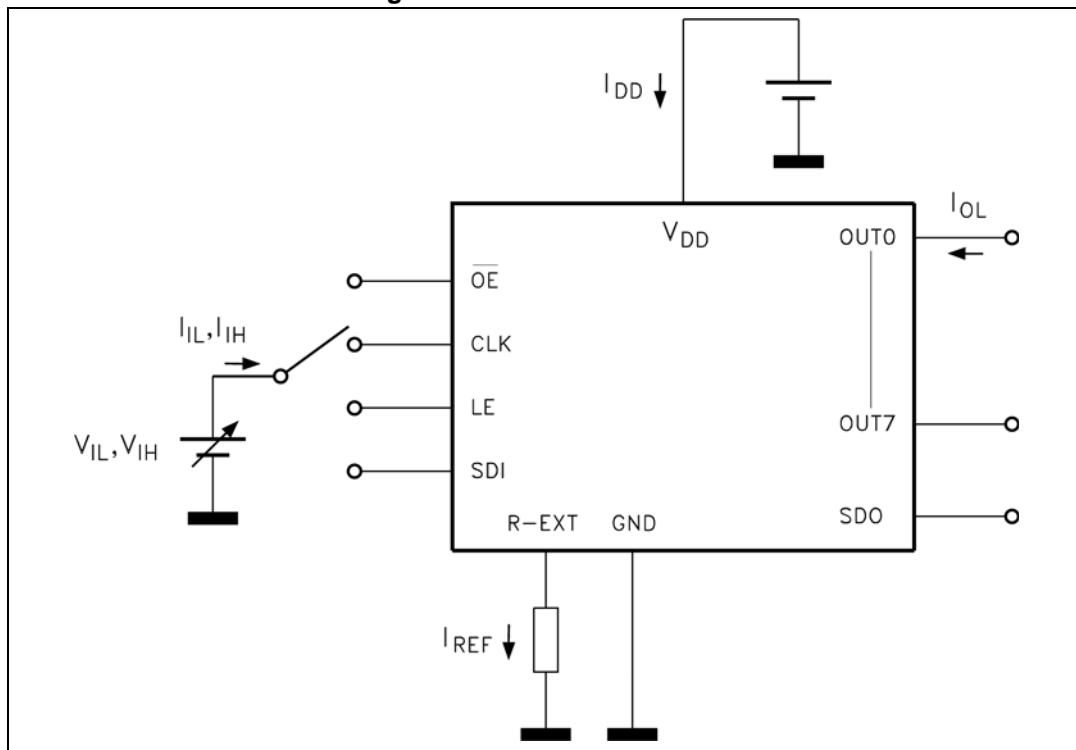
**Figure 13. Power dissipation vs temperature package**

*Note:* The exposed-pad should be soldered to the PBC to realize the thermal benefits.

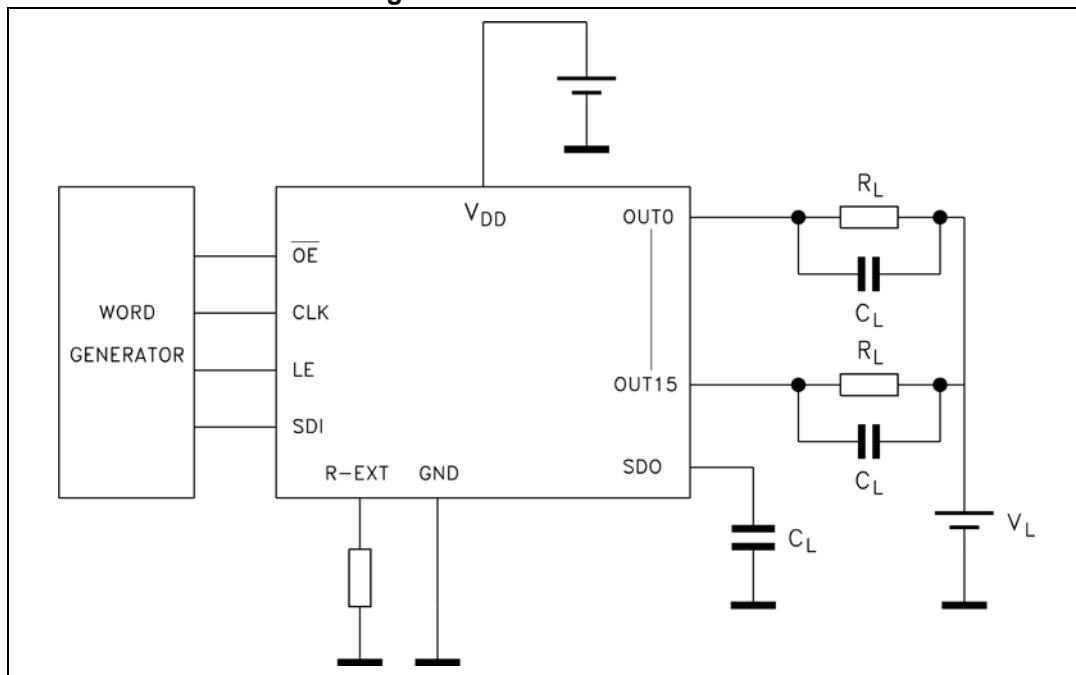
**Figure 14. Current precision between outputs vs output current**

## 9 Test circuit

**Figure 15. DC characteristics**



**Figure 16. AC characteristics**



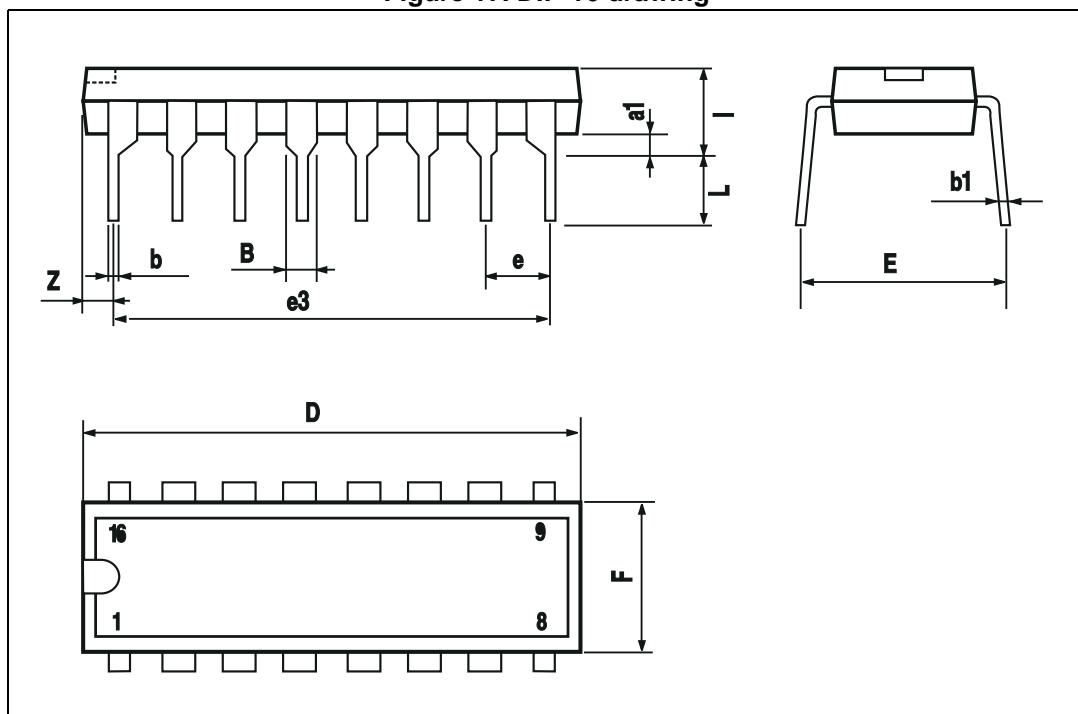
## 10 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com).  
ECOPACK® is an ST trademark.

Table 12. DIP-16 mechanical data

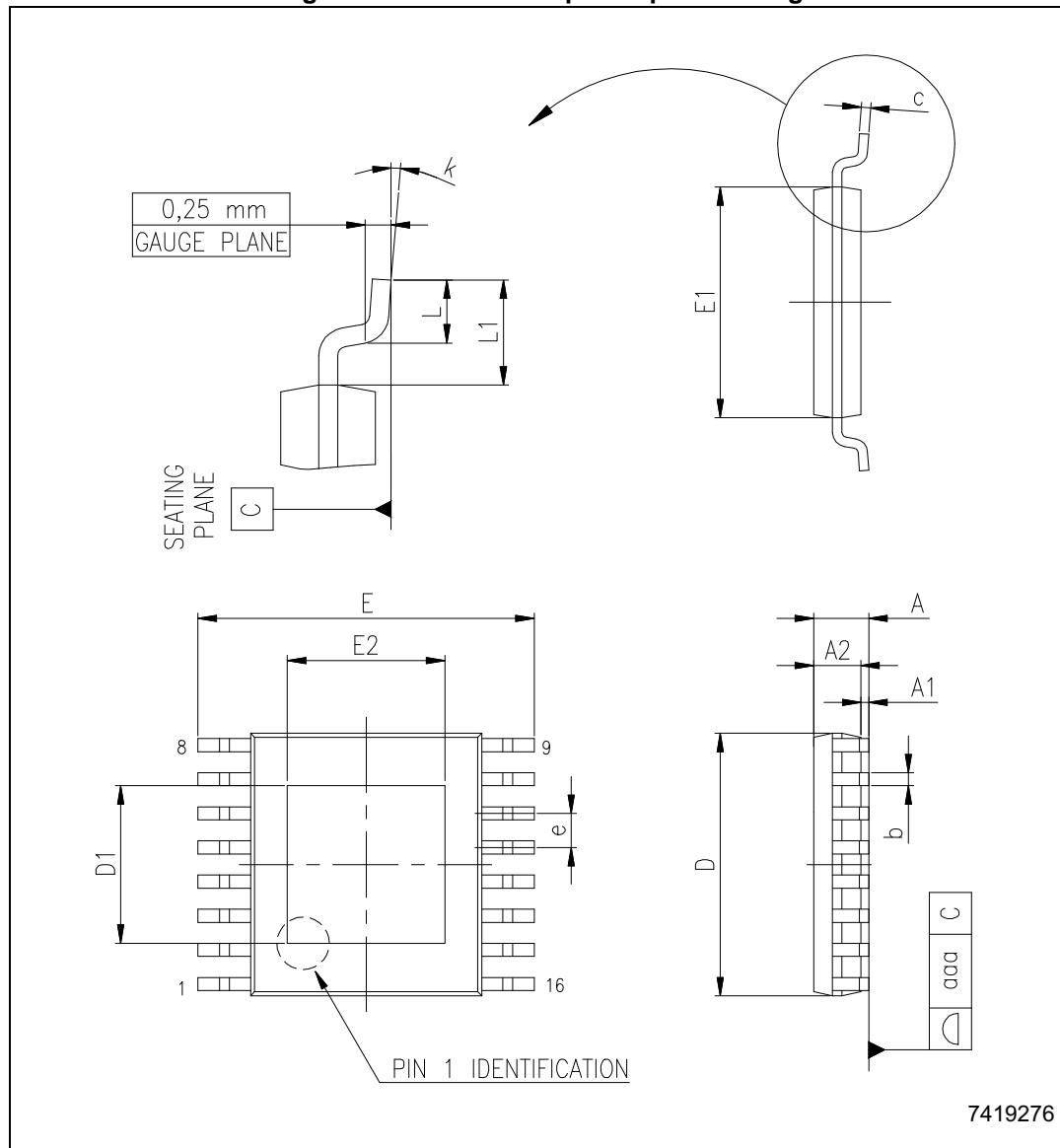
Dim.	mm		
	Min.	Typ.	Max.
a1	0.51		
B	0.77		1.65
b		0.5	
b1		0.25	
D			20
E		8.5	
e		2.54	
e3		17.78	
F			7.1
I			5.1
L		3.3	
Z			1.27

Figure 17. DIP-16 drawing



**Table 13. TSSOP16 exposed pad mechanical data**

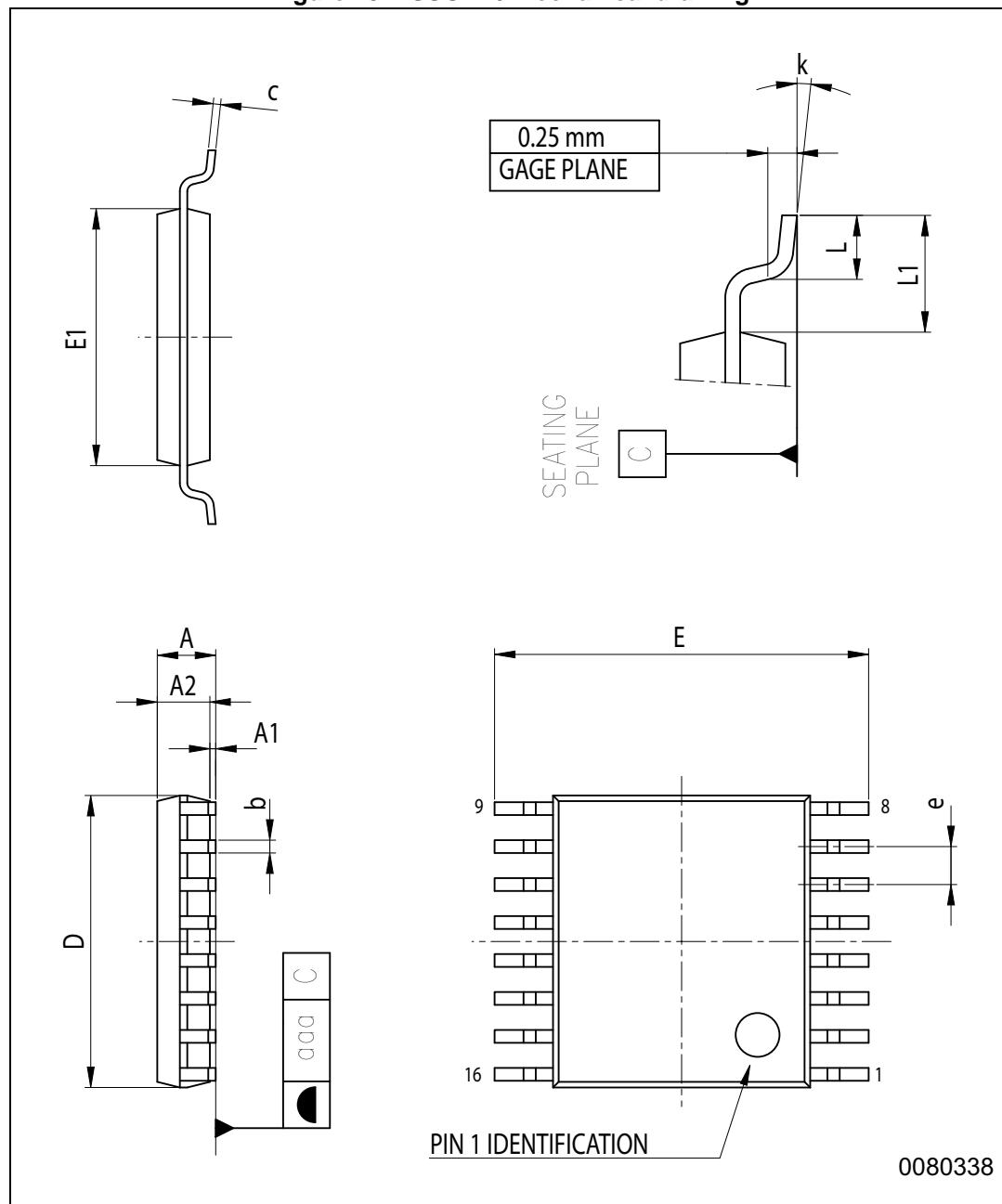
Dim.	mm		
	Min.	Typ.	Max.
A			1.20
A1			0.15
A2	0.80	1.00	1.05
b	0.19		0.30
c	0.09		0.20
D	4.90	5.00	5.10
D1		3.00	
E	6.20	6.40	6.60
E1	4.30	4.40	4.50
E2		3.00	
e		0.65	
L	0.45	0.60	0.75
L1		1.00	
k	0.00		8.00
aaa			0.10

**Figure 18. TSSOP16 exposed pad drawing**

**Table 14. TSSOP16 mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A			1.20
A1	0.05		0.15
A2	0.80	1.00	1.05
b	0.19		0.30
c	0.09		0.20
D	4.90	5.00	5.10
E	6.20	6.40	6.60
E1	4.30	4.40	4.50
e		0.65	
L	0.45	0.60	0.75
L1		1.00	
k	0		8
aaa			0.10

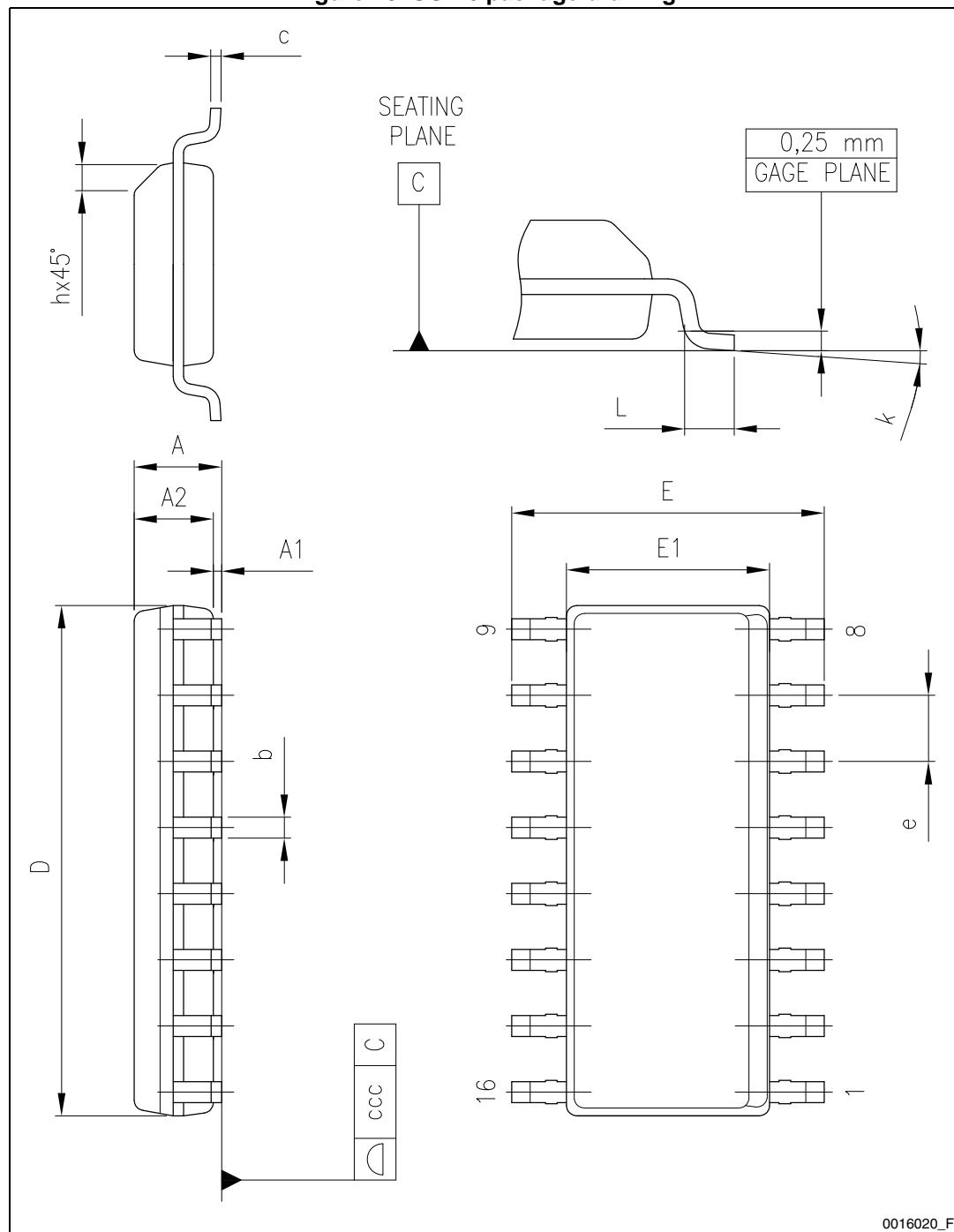
Figure 19. TSSOP16 mechanical drawing

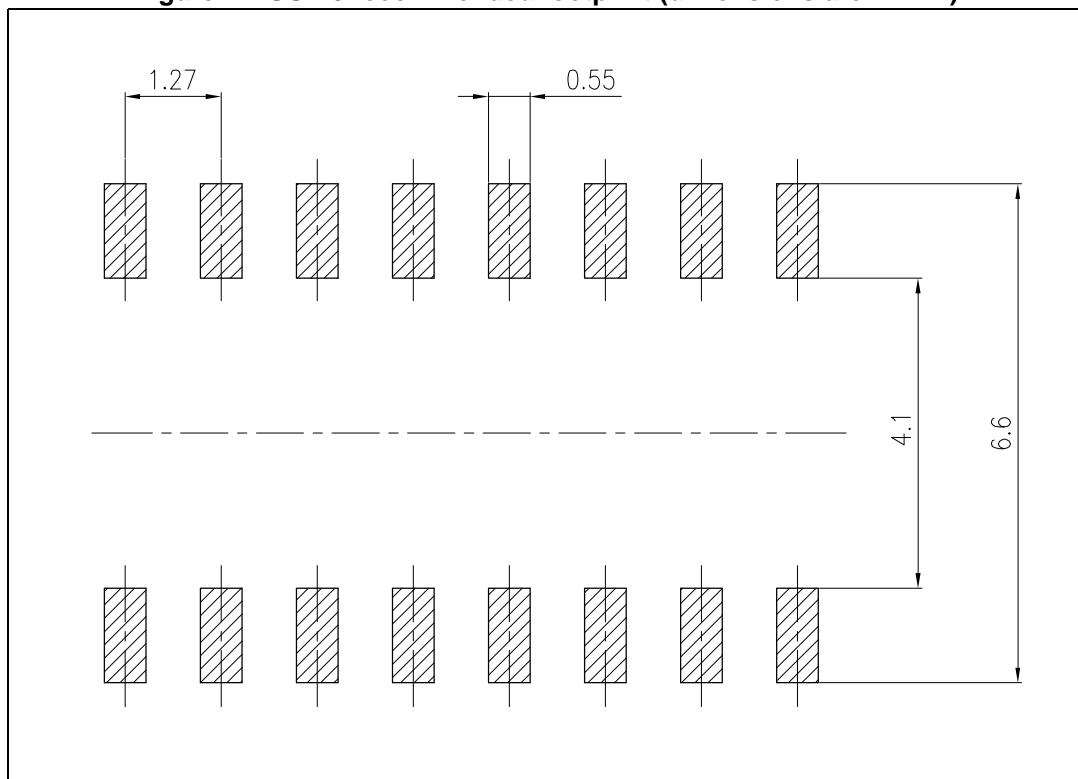


**Table 15. SO-16 dimensions**

Dim.	mm		
	Min.	Typ.	Max.
A			1.75
A1	0.10		0.25
A2	1.25		
b	0.31		0.51
c	0.17		0.25
D	9.80	9.90	10.00
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e		1.27	
h	0.25		0.50
L	0.40		1.27
k	0		8°
ccc			0.10

Figure 20. SO-16 package drawing

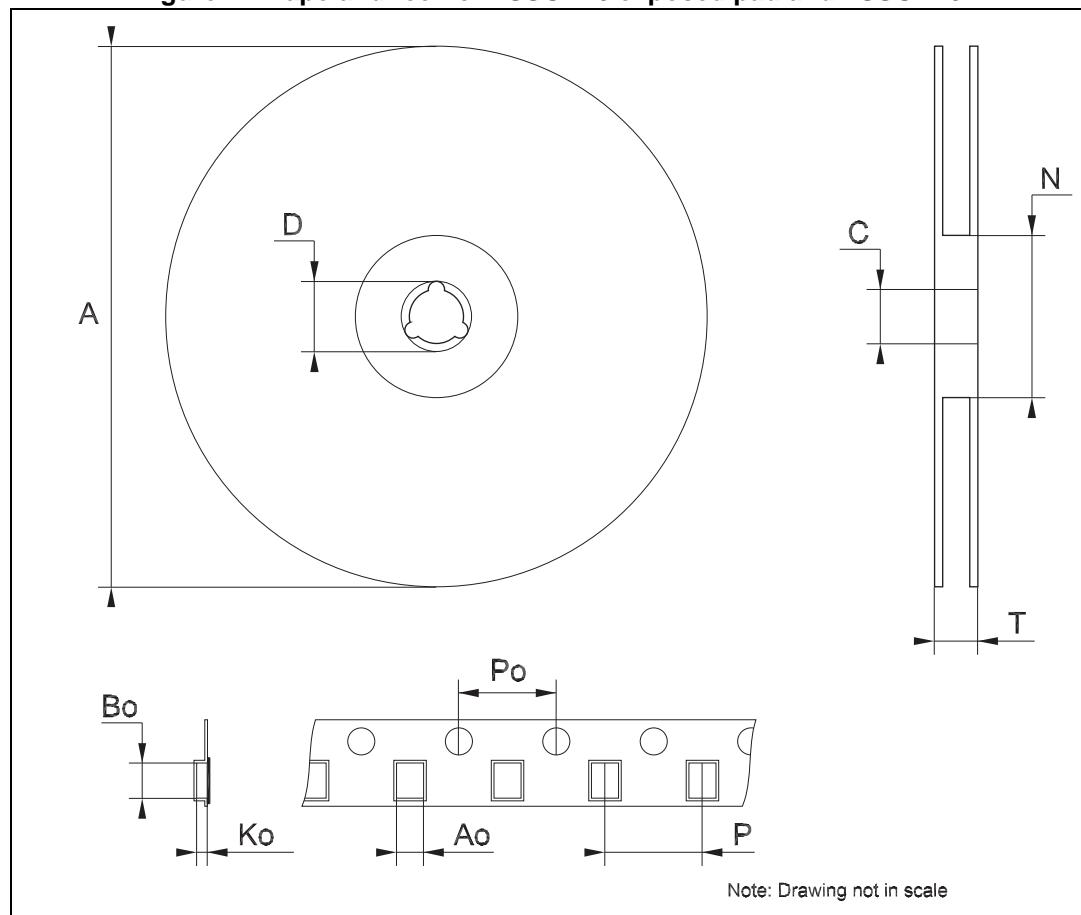


**Figure 21. SO-16 recommended footprint (dimensions are in mm)**

## 11 Packaging mechanical data

**Table 16. TSSOP16 exposed pad and TSSOP16 tape and reel mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A			330
C	12.8		13.2
D	20.2		
N	60		
T			22.4
Ao	6.7		6.9
Bo	5.3		5.5
Ko	1.6		1.8
Po	3.9		4.1
P	7.9		8.1

**Figure 22. Tape and reel for TSSOP16 exposed pad and TSSOP16**

## 12 Revision history

**Table 17. Document revision history**

Date	Revision	Changes
23-May-2007	1	First release
28-Jun-2007	2	Updated Table 7 on page 7
12-Mar-2008	3	Updated Table 8 on page 8 and added Figure 11 and Figure 12 on page 15
07-Aug-2008	4	Updated Section 8: Typical characteristics on page 14
27-Aug-2010	5	Updated Note: on page 3
10-Jul-2013	6	Updated Section 10: Package mechanical data, Figure 3: OE terminal and Figure 4: LE terminal Added Section 11: Packaging mechanical data
28-Jun-2018	7	Updated: Table 14: TSSOP16 mechanical data and Figure 20: TSSOP16 mechanical drawing
29-Aug-2018	8	Updated: <i>Figure 7: Timing diagram, Figure 8: Clock, serial-in, serial-out, Figure 9: Clock, serial-in, latch, enable, outputs, Figure 10: Outputs, Figure 15: DC characteristics and Figure 16: AC characteristics.</i> Minor text changes.

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ООО "ЛайфЭлектроникс"

"LifeElectronics" LLC

ИНН 7805602321 КПП 780501001 Р/С 40702810122510004610 ФАКБ "АБСОЛЮТ БАНК" (ЗАО) в г.Санкт-Петербурге К/С 30101810900000000703 БИК 044030703

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибуторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибуторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помочь разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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